

Amendments to the Claims:

1-10. (Cancelled)

11. (Original) A copper-clad laminate for use in a method of forming a penetration hole for a through hole in a thermosetting resin copper-clad laminate having at least two copper layers, in which copper foils of the thermosetting resin copper-clad laminate are processed with an energy of 20 to 60 mJ/pulse sufficient for removing the copper foils by means of the pulse oscillation of a carbon dioxide gas laser, the copper-clad laminate being a copper-clad laminate containing a prepreg of a glass fabric substrate which is impregnated with a resin composition containing a thermosetting resin having a glass transition temperature of at least 150°C and 10 to 60 % by weight an insulating inorganic filler, the copper-clad laminate having a cross section wherein the thermosetting resin and the inorganic filler from the resin composition are homogeneously mixed.

12. (Currently Amended) The ~~A~~ copper-clad laminate according to claim 11, wherein the thermosetting resin composition contains 0.1 to 10 % by weight of a black or brown dye or pigment.

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13. (Currently Amended) An auxiliary material which is for use on a copper foil surface of a copper-clad laminate when a penetration hole is made in the copper-clad laminate with a carbon dioxide gas laser by irradiating the copper foil surface with an energy of 20 to 60 mJ/pulse sufficient by means of the pulse oscillation of a carbon dioxide gas laser, and which is a coating or a sheet of an organic substance containing 3 to 97 % by volume of at least one powder selected from the group consisting of a metal compound powder, having a melting point of at least 900°C and a bond energy of at least 300 KJ/mol, a carbon powder and metal powder ~~which have a melting point of at least 900°C and a bond energy of at least 300 KJ/mol~~.

14. (Currently Amended) The ~~An~~ auxiliary material according to claim 13, wherein the organic substance is a water-soluble resin composition.

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15. (Currently Amended) The ~~An~~ auxiliary material according to claim 13, wherein the sheet is a product formed by bonding a water-soluble resin composition to one surface of a thermoplastic film.

16. (Currently Amended) The ~~An~~ auxiliary material according to claim 15, wherein the sheet is a product in which the total thickness of the layer of the water-soluble resin composition and the thermoplastic film is 30 to 200  $\mu\text{m}$ .

17. (Currently Amended) The ~~An~~ auxiliary material according to claim 15, wherein the sheet is used by disposing the layer of the water-soluble resin composition on the copper foil surface side and laminating the layer of the water-soluble resin composition to the copper foil under heat and under pressure.

18. (Currently Amended) The ~~An~~ auxiliary material according to claim 15, wherein the sheet is used by wetting the surface of the layer of the water-soluble resin composition 3  $\mu\text{m}$  or less deep with water in advance, disposing the layer of the water-soluble resin composition on the copper foil surface side and laminating under pressure at room temperature.

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19. (Original) A backup sheet for making a hole with a carbon dioxide gas laser, which is for use on a reverse outermost copper foil surface of a copper-clad laminate when a hole is made in the copper-clad laminate with a carbon dioxide gas laser by irradiating a front copper foil surface with an energy of 20 to 60 mJ/pulse by means of the pulse oscillation of a carbon dioxide gas laser and which comprises a 20 to 200  $\mu\text{m}$  thick resin layer and a metal plate.

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20. (Currently Amended) The ~~A~~ backup sheet according to claim 19, wherein the resin layer is a water-soluble resin composition.

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